



The VERSAPRINT B1 is the ideal printer to enter line production and is perfectly suitable for customers expecting a perfect print result in combination with an easy to use printer system. The printer is equipped with an area camera that uses two separate camera modules. Both modules have two illumination techniques: direct and diffuse illumination, thus qualifying them to recognize even most complicated structures on the substrate.

Integrated in the standard system, the programmable automatic stencil cleaning system ensure quick and efficient cleaning results of the bottom side of the stencil whenever a cleaning cycle is necessary.

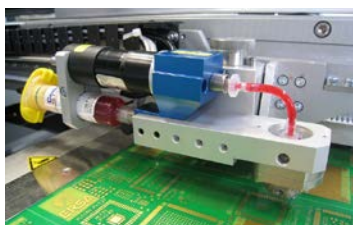
A wide range of options are available to configure the B1 printer for production needs. Setup control, Data Matrix Code reader, retractable over top clamping, air conditioning and PCB dispenser are only a few examples of the options available.

Combining the VERSAPRINT B1 with an SPI system the closed loop function feedbacks the result to the printer which could be used to optimize the printing process.

Certainly the printer can be equipped with the optional available 2D inspection to verify the position, quality and the risk of shorts for glue or solder paste printing. On the stencil the apertures and under stencil smearing will be inspected.

Optional features for Ersa VERSAPRINT B1	
PCB Inspection: paste on pad, recognition of solder bridges and print offset	<input type="checkbox"/>
Stencil inspection: clogging and smearing	<input type="checkbox"/>
Dispenser for print media on stencil	<input type="checkbox"/>
Dispenser for glue or paste on the substrate	<input type="checkbox"/>
Paste height control – stencil	<input type="checkbox"/>
Retractable over-top clamping	<input type="checkbox"/>
Temperature control	<input type="checkbox"/>
Data Matrix Code reader – top- and bottom side	<input type="checkbox"/>
Setup control	<input type="checkbox"/>
Support systems: VarioGrid, GridLok and Quik-Tool	<input type="checkbox"/>
Closed loop printer - SPI	<input type="checkbox"/>

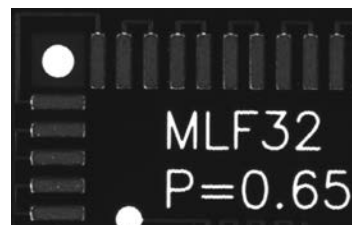
Standard ■ / Option □



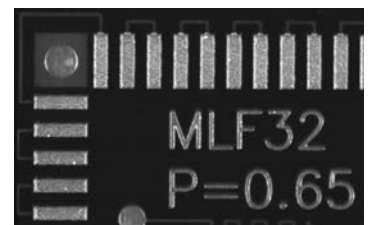
Dispenser (PCB)



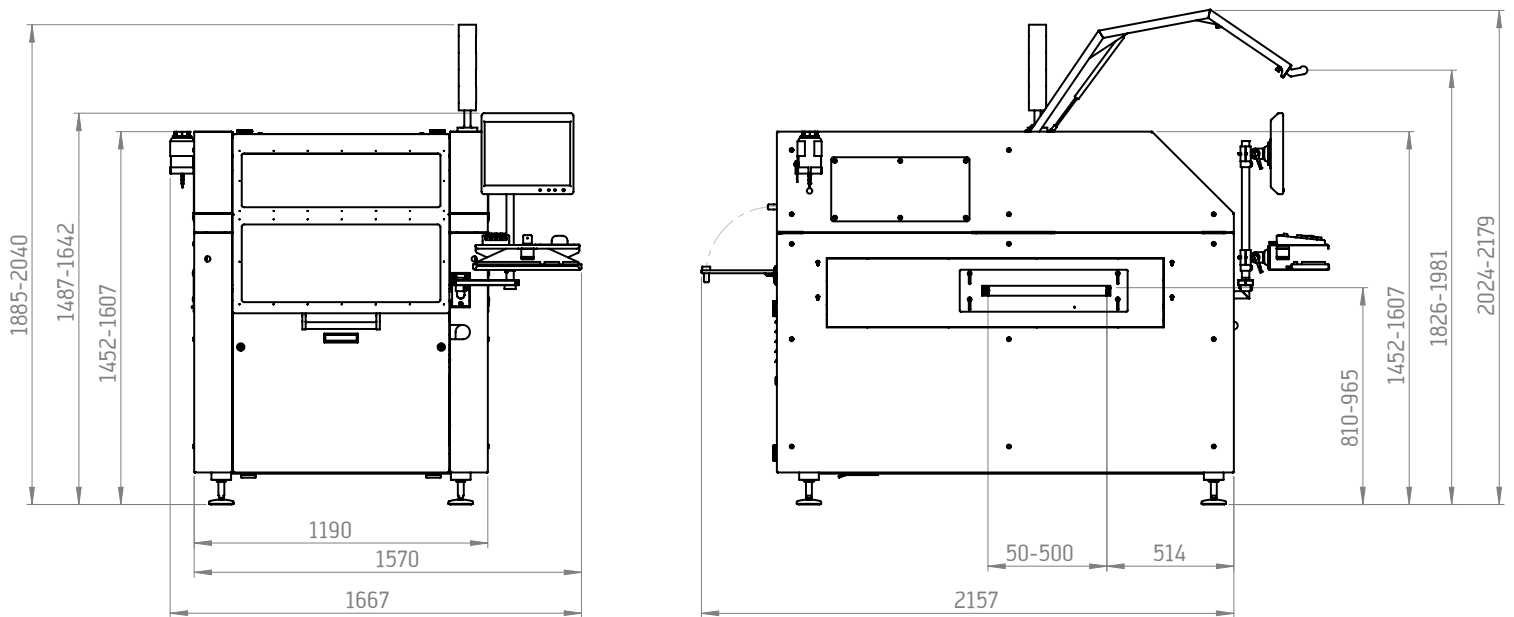
Maintenance: Squeegee cleaning



Direct lighting



Diffuse lighting



Substrate handling

min. substrate size (X x Y):	80 x 50 mm
max. substrate size (X x Y):	550 x 500 mm
Substrate thickness:	0.5 – 6 mm
Component clearance:	0 – 30 mm

Stencil mount

stencil size:	min. 450 x 450 mm – max. 737 x 737 mm, adjustable without adapter
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Print parameters

Print head:	two independent print heads; continuous pressure control in a closed-loop system; adjustable squeegee down stop weight compensation for different squeegee length
Print force:	0 – 260 N

Vision

Camera:	area camera for alignment and inspection
FOV (field of view):	10.5 x 8 mm

Performance

Repeatability:	± 12.5 µm @ 6 Sigma
Print accuracy:	± 25 µm @ 6 Sigma
Cycle time:	< 10 s + print
Setup time:	< 10 min
Product change:	< 2 min

Machine operation

Graphic user interface:	SEMI Standard E95-1101
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Machine dimensions

Width:	1,190 mm
Depth:	1,770 mm
Height:	1,600 mm
Weight:	1,070 kg
Colour:	RAL 7035/7016